

METHOD AND DEVICE TO ELONGATE A SOLDER JOINT

Abstract

A method and device to elongate a solder joint are provided. The method begins by forming an elongator on a first substrate. The elongator comprises an expander and an
5 encapsulant to encapsulate the expander. A solder joint is formed to connect the first substrate to a second substrate. Thereafter, the encapsulant is softened to release the expander from a compressed state to elongate the solder joint. The device to elongate a solder joint comprises a substrate having an elongator formed on it. The elongator includes an expander in a compressed state and an encapsulant to encapsulate the
10 expander.

Figure 8c